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# **microSD™, microSDHC™ and microSDXC™ Cards**

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## **OEM Product Manual**

Revision 3.7

Document No. 80-36-03335

September 2015

### **SanDisk Corporation**

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**Revision History**

<b>Date</b>	<b>Revision</b>	<b>Description</b>
July 2008	1.0	First Revision
June 2010	2.0	Added 32 GB Replaced SD 2.0 with SD 3.0 ACMD41 to ready after power up updated Updated marking, section 5 Updated Tables 7, 9, and 11 to remove < 1G references Updated Figure 1 – SD card block diagram
March 2011	2.1	Added speed class to Ordering Information Table
April 2011	2.2	Added 64GB and updated SDA 3.0 to SD3.UHS-I 50
October 2011	2.3	Added SDSAQAC SKUs to Ordering Information. Updated Figure 7 to add High Performance figure.
November 2011	2.4	Added Ordering Information.
January 2012	2.5	Reference to SDA corrections. Added SDSAQAD SKUs to Ordering Information
July 2012	2.6	Marking info updated with alternate laser marking guide and Premier microSD product marking info
July 2013	3.0	Removed High Performance line (SDSAQAC)
November 2013	3.1	Added SDSAQAE SKUs Removed SDSAQ SKUs Removed random IOPs performance from ordering information
February 2014	3.2	Updated Table 2: Card Power and Section 6: Ordering information
May 2014	3.3	Added 128GB microSD – SDSAQAD-128G Updated Table 10
June 2014	3.4	Remove figures 4 and 5. Update Table 2. Update Section 5.
July 2014	3.5	Updated section 1.1 and 1.2, from 64GB to 128GB
October 2014	3.6	Updated CID Register
September 2015	3.7	Added 200GB part number

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# 1 INTRODUCTION

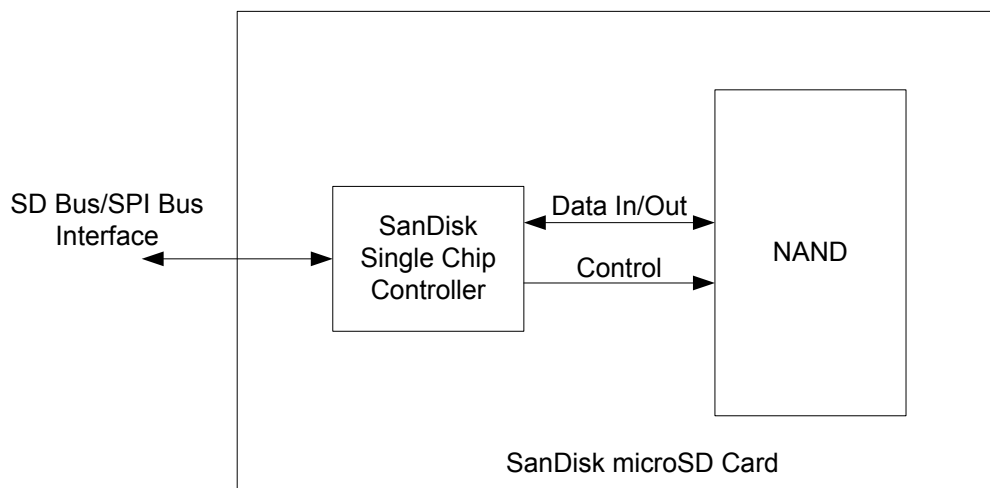
## 1.1 General Description

SanDisk's microSD™, microSDHC™ (High Capacity) and microSDXC™ (Extended Capacity) cards are flash based removable non-volatile memory devices specifically designed to meet the security, capacity, performance and environmental requirements inherent in next generation mobile phones and consumer electronic devices.

The microSD card includes a content protection system that complies with the security of the Secure Digital Music Initiative (SDMI) standard and has a higher memory capacity. In the microSD card, card content is protected from unauthorized use by mutual authentication and a cipher algorithm. Unsecured access to the user's own content is also available.

microSD cards are based on an 8-pin interface designed to operate in a maximum operating frequency of 208 MHz. The interface for microSD card products allows for easy integration into any design, regardless of which type of microprocessor is used. In addition to the interface, microSD card products offer an alternate communication-protocol based on the SPI standard.

SanDisk's microSD card Product Family provides up to 200 gigabytes (GB)<sup>1</sup> of memory using flash memory chips, which were designed especially for use in mass storage applications. In addition to the mass storage-specific flash memory chip, cards in the microSD card product family includes an on-board intelligent controller which manages interface protocols; security algorithms for content protection; data storage and retrieval, as well as Error Correction Code (ECC) algorithms; defect handling; power management; wear leveling, and clock control.



**Figure 1: SanDisk's microSD Card Block Diagram**

<sup>1</sup> 1 Gigabyte (GB) = 1 billion bytes. Some capacity is not available for data storage.

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## 1.2 Features

General features of cards in the SanDisk microSD Memory Card Product Family include:

- Up to 200 GB<sup>2</sup> of data storage
- SD - protocol compatible
- Supports SPI Mode
- Targeted for portable and stationary applications for secured (content protected) and unsecured data storage
- Voltage range of 2.7 to 3.6V
- Variable clock rate 0-25 MHz (standard), 0-50 MHz (high performance), 0-208 MHz (Ultra High Speed)
- Up to 104 MB/sec\* data transfer rate (using four parallel data lines)
- Memory field error correction
- Content protection mechanism that complies with highest security of SDMI standard
- Password protection
- Built-in write protection features (permanent and temporary)
- Supports card detection (insertion and removal)
- Application-specific commands

## 1.3 Scope

This document describes key features and specifications of the microSD cards as well as the information required to interface these products to a host system. Chapter 2 describes the physical and mechanical properties of cards in the microSD card product family, Chapter 3 contains the pins and register overview, and

Chapter 4 gives a general overview of the SD protocol. Information about SPI Protocol can be referenced in Section 7 of the SDA Physical Layer Specification, Version 3.01.

## 1.4 SD Card Standard

SanDisk's microSD memory cards are fully compatible with the SDA Physical Layer Specification, Version 3.01. This specification is available from the SD Card Association (SDA).

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Web site: [www.sdcard.org](http://www.sdcard.org)

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<sup>2</sup> 1 Gigabyte (GB) = 1 billion bytes. Some capacity is not available for data storage.



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## **1.5 Functional Description**

The family of SanDisk microSD cards contains a high-level, intelligent subsystem as shown in Figure 1. This intelligent (microprocessor) subsystem provides many capabilities not found in other types of memory cards. These capabilities include:

- Host independence from details of erasing and programming flash memory
- Sophisticated system for managing defects (analogous to systems found in magnetic disk drives)
- Sophisticated system for error recovery including a powerful ECC
- Power management for low power operation

### **1.5.1 Technology Independence**

The 512-byte sector size of a card in the microSD card product family is the same as that in an IDE magnetic disk drive. To write or read a sector (or multiple sectors), the host software simply issues a read or write command to the card. The command contains the address and number of sectors to write or read. The host software then waits for the command to complete.

The host software does not get involved in the details of how the flash memory is erased, programmed or read. This is extremely important because flash devices are expected to get increasingly complex in the future. Because cards in the SanDisk microSD Card Product Family use an intelligent on-board controller, host system software will not need to be updated as new flash memory evolves. In other words, systems that support the microSD Card Product Family today will be able to access future SanDisk cards built with new flash technology without having to update or change host software.

### **1.5.2 Defect and Error Management**

The SanDisk microSD Card Product Family contains a sophisticated defect and error management system. This system is analogous to the systems found in magnetic disk drives and in many cases offers enhancements. If necessary, SanDisk microSD Card Product Family will rewrite data from a defective sector to a good sector. This is completely transparent to the host and does not consume any user data space. In the extremely rare case that a read error does occur, SanDisk microSD Memory Card Product Family has innovative algorithms to recover the data. These defect and error management systems, coupled with the solid state construction, give SanDisk microSD Card Product Family enormous reliability.

### **1.5.3 Content Protection**

A detailed description of the content protection mechanism and related security SD commands can be found in the SD Security Specification from the SDA. All SD security-related commands in the SanDisk microSD Card Product Family operate in the data transfer mode.

### **1.5.4 Wear Leveling**

Wear leveling is an intrinsic part of the erase pooling functionality of cards in the SanDisk microSD Card Product Family using NAND memory.

### **1.5.5 Automatic Sleep Mode**

A unique feature of cards in the SanDisk microSD Card Product Family is automatic entrance and exit from sleep mode. Upon completion of an operation, cards enter

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sleep mode to conserve power if no further commands are received in less than 5 milliseconds (ms). The host does not have to take any action for this to occur. However, in order to achieve the lowest sleep current, the host needs to shut down its clock to the card. In most systems, cards are in sleep mode except when accessed by the host, thus conserving power.

When the host is ready to access a card in sleep mode, any command issued to it will cause it to exit sleep, and respond.

### **1.5.6 Hot Insertion**

Support for hot insertion will be required on the host but will be supported through the connector. Connector manufacturers will provide connectors that have power pins long enough to be powered before contact is made with the other pins.

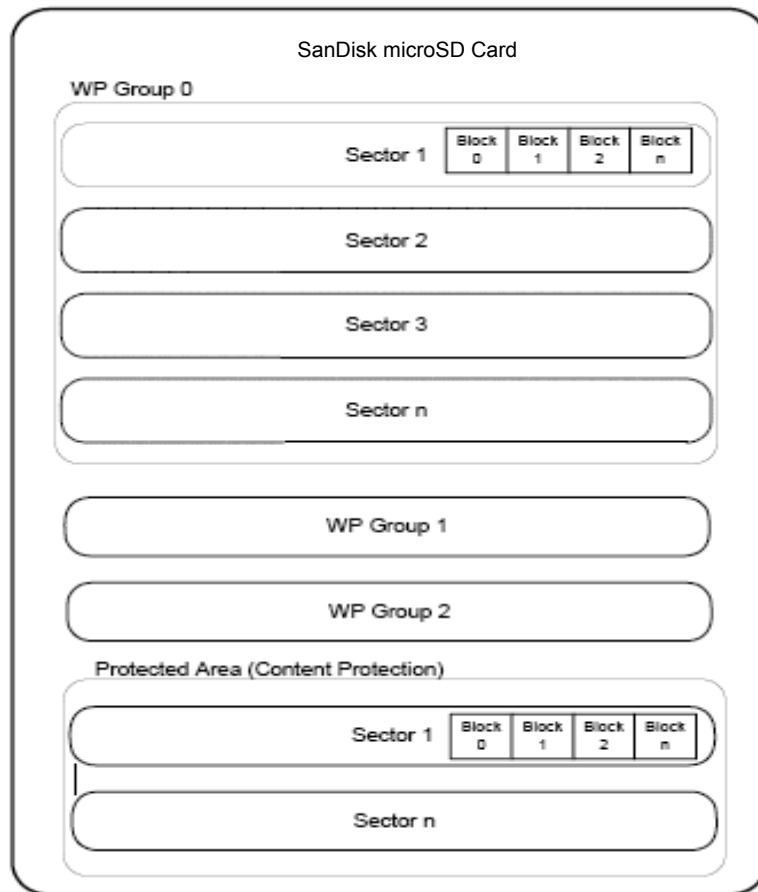
## **1.6 *microSD Card Products in SD Bus Mode***

The following sections provide valuable information on cards in the SanDisk microSD Card Product Family in SD Bus mode.

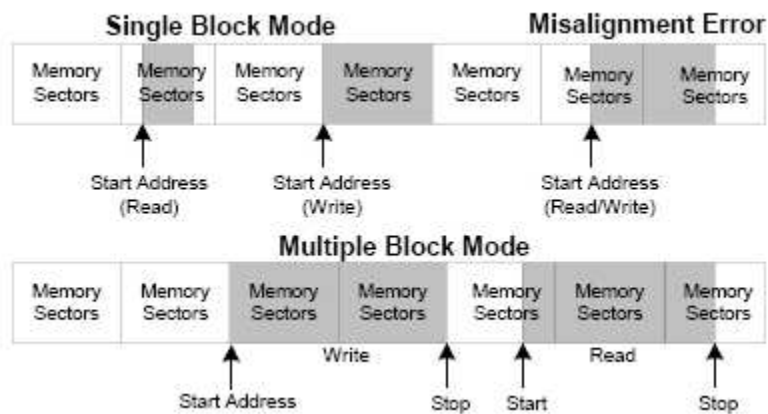
Cards in the SanDisk microSD Card Product Family are fully compliant with the SDA Physical Layer Specification, Version 3.01. Card Specific Data (CSD) Register structures are compliant with CSD Structure 1.0 and 2.0.

This section covers Negotiating Operating Conditions, Card Acquisition and Identification, Card Status, Memory Array Partitioning, Read/Write Operations, Data Transfer Rate, Data Protection in Flash Cards, Write Protection, Copy Bit, and CSD Register.

Additional practical card detection methods can be found in application notes pertaining to the SDA Physical Layer Specification, Version 3.01.



**Figure 2: Memory Array Partitioning**



**Figure 3: Data Transfer Formats**

Table 1 contains descriptions for each transfer mode.

**Table 1: Mode Descriptions**

Mode	Description
Single Block	<p>In this mode the host reads or writes one data block in a pre-specified length. The data block transmission is protected with 16-bit CRC that is generated by the sending unit and checked by the receiving unit.</p> <p>The block length for read operations is limited by the device sector size (512 bytes) but can be as small as a single byte. Misalignment is not allowed. Every data block must be contained in a single physical sector.</p> <p>The block length for write operations must be identical to the sector size and the start address aligned to a sector boundary.</p>
Multiple Block	<p>This mode is similar to the single block mode, except for the host can read/write multiple data blocks (all have the same length) that are stored or retrieved from contiguous memory addresses starting at the address specified in the command. The operation is terminated with a stop transmission command.</p> <p>Misalignment and block length restrictions apply to multiple blocks and are identical to the single block read/write operations.</p>

## 1.7 SPI Mode

The SPI Mode is a secondary communication protocol for cards in the SanDisk microSD Card Product Family. This mode is a subset of the SD Protocol, designed to communicate with an SPI channel, commonly found in Motorola and other vendors' microcontrollers. Detailed information about SPI Mode can be found in Section 7 or the SDA Physical Layer Specification, Version 3.01.

## 2 PRODUCT SPECIFICATIONS

### 2.1 microSD Card Product Family

This section provides product specifications for the microSD Card Product Family. For more details about the environmental, reliability and durability specifications, refer the SDA Physical Layer Specification, Version 3.01 and microSD card addendum v3.0.

#### 2.1.1 Typical Card Power Requirements

The values stated in Table 2 represent the SanDisk microSD Card power requirements.

**Table 2: microSD Card Power Requirements**

Mode	Maximum Value	Typical Value at 25C
<b>Standard Mode (25 MHz)</b>		
Sleep		500 uA 600 uA (128/200GB)
Read	100 mA	
Write	100 mA	
<b>Standard Mode – for SDXC card - XPC bit on (25 MHz)</b>		
	Host selected XPC bit in ACMD41	
Sleep		500 uA 600 uA (128/200GB)
Read	150 mA	
Write	150 mA	
<b>High Performance Mode (50 MHz)</b>		
Sleep		500 uA 600 uA (128/200GB)
Read	200 mA	
Write	200 mA	
<b>UHS-I SDR50 Mode – (100 MHz)</b>		
Sleep		500 uA 600 uA (128/200GB)
Read	400 mA	
Write	400 mA	
<b>UHS-I DDR50 Mode – (50 MHz)</b>		
Sleep		500 uA 600 uA (128/200GB)
Read	400 mA	
Write	400 mA	
<b>UHS-I SDR104 Mode – (208 MHz)</b>		
Sleep		500 uA 600 uA (128/200GB)
Read	800 mA	
Write	800 mA	

Note: Current consumption is measured by averaging over one (1) second. Refer to Section 6.6.3 of the SDA Physical Layer Specification, Version 3.01 for more information

### 2.1.2 System Performance

This section provides the system performance specifications for the SanDisk microSD Card Product Family. All performance values in Table 3 were measured under the following conditions:

- Voltage range 2.7 to 3.6V
- Operating temperature -25°C to 85°C
- Independent of card clock frequency

**Table 3: System Performance**

Timing	Maximum Value
Block Read Access Time	100 ms
Block Write Access Time	250 ms for SDHC, 500 ms for SDXC
ACMD41 to ready after power-up	1s

---

### **2.1.3 Reliability and Durability**

For microSD environmental, reliability and durability specifications, refer to SDA Physical Layer Specification, Version 3.01 and microSD Card Addendum v3.0.

### **2.1.4 Physical Specifications**

For detail dimensions and tolerances refer to SDA microSD Card Addendum, Mechanical Specification for microSD Memory Card.

## 3 INTERFACE DESCRIPTION

### 3.1 Pins and Registers

The microSD Card Product Family has exposed contacts on one side. The host uses a dedicated connector to connect to microSD cards.

In Table 4, pin assignments for the microSD Card are described for SD Bus Mode and SPI Bus Mode

Note: Pin assignments are provided by the SDA Physical Layer Specification, Version 3.01 and associated addendums (microSD). For more details, refer to Section 3.7 of the SDA Physical Layer Specification, Version 3.01

**Table 4: SD Bus Mode Pin Assignment**

Pin No.	SD Mode			SPI mode		
	Name	Type <sup>1</sup>	Description	Name	Type <sup>1</sup>	Description
1	DAT2 <sup>2,5</sup>	I/O/PP	Data Line [bit 2]	RSV	-	Reserved
2	CD/DAT3 <sup>2</sup>	I/O/PP <sup>3</sup>	Card Detect/Data Line [bit 3]	CS	I <sup>3</sup>	Chip select (active low)
3	CMD	PP	Command/Response	DataIn	I	Data In
4	V <sub>DD</sub>	S	Supply Voltage	V <sub>DD</sub>	S	Supply Voltage
5	CLK	I	Clock	SCLK	I	Clock
6	V <sub>SS</sub>	S	Supply voltage ground	V <sub>SS</sub>	S	Supply voltage ground
7	DAT0	I/O/PP	Data Line [bit 1]	DataOUT	O/PP	Data Out
8	DAT1 <sup>2,4</sup>	I/O/PP	Data Line [bit 2]	RSV <sup>4</sup>	-	Reserved

- Notes:
1. Type Key: S=power supply; I=input; O=output using push-pull drivers; PP=I/O using push-pull drivers.
  2. The extended DAT lines (DAT1-DAT3) are input on power up. They start to operate as DAT lines after the SET\_BUS\_WIDTH command. It is the responsibility of the host designer to connect external pull-up resistors to all data lines even if only DAT0 is to be used. If not, there may be unexpected high current consumption due to the floating inputs of DAT1 & DAT2 (if they are not used).
  3. At power up this line has a 50 kilohm pull-up enabled in the card. This resistor serves two functions: Card Detection and Mode Selection. For Mode Selection, the host can drive the line high or let it be pulled high to select SD mode. If the host wants to select SPI mode, it should drive the line low. For Card Detection, the host detects that the line is pulled high. The user should disconnect this pull-up with SET\_CLR\_CARD\_DETECT (ACMD42) command during regular data transfer.
  4. DAT1 line may be used as Interrupt Output (from the Card) in SDIO mode during all the times that it is not in use for data transfer operations.
  5. DAT2 line may be used as Read Wait signal in SDIO mode.



Each card has a set of information registers. Register descriptions and SDA references are provided in Section 5.0 of the SDA Physical Layer Specification, Version 3.01.

**Table 5: microSD Card Product Family Register Overview**

Register Abbreviation	Width (in bits)	Register Name
CID	128	Card identification number
RCA	16	Relative card address
CSD	128	Card specific data
SCR	64	SD configuration register
OCR	32	Operation condition register
SSR	512	SD status register
CSR	32	Card status register

## 3.2 Bus Topology

The family of microSD products supports two communication protocols: SD and SPI. For more details, refer to Section 3.5 of the SDA Physical Layer Specification, Version 3.01. Section 6 of the specification contains a bus circuitry diagram for reference.

### 3.2.1 SD Bus

For more details, refer to Section 3.5.1 of the SDA Physical Layer Specification, Version 3.01.

### 3.2.2 SPI Bus

For more details, refer to Section 3.5.2 of the SDA Physical Layer Specification, Version 3.01.

## 3.3 Hot Insertion and Power Protection

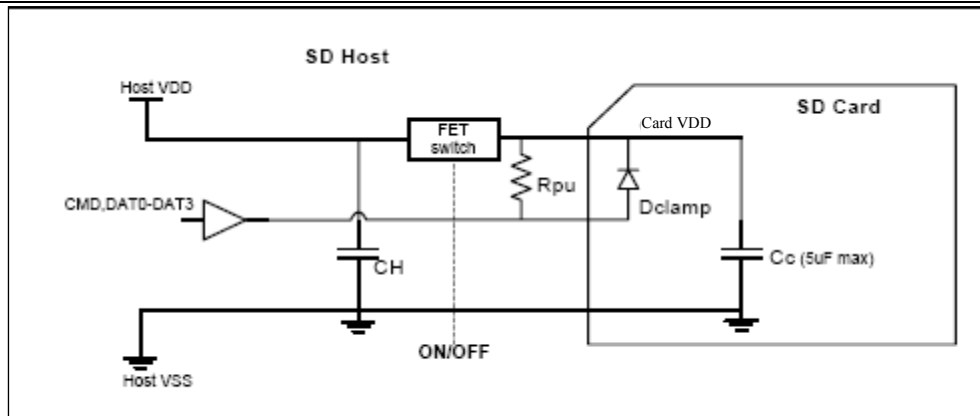
Refer to Section 6.1 and Section 6.2 of the SDA Physical Layer Specification, Version 3.01.

## 3.4 Electrical Interface

The power scheme of microSD products is handled locally in each card and in the bus master. Refer to Section 6.4 of the SDA Physical Layer Specification, Version 3.01.

### 3.4.1 Power Up

Power must be applied to the VDD pin before any I/O pin is set to logic HIGH. In other words, CMD, CLK, and DAT0-3 must be at zero (0) volts when power is applied to the VDD pin. For more information, refer to Section 6.4.1 of the SDA Physical Layer Specification, Version 3.01.



**Figure 4: Recommended Power Control Scheme**

The recommended power control scheme for microSD cards is illustrated in Figure 4. Most card connectors have a card detect switch that signals the SD host when the card is inserted. After the host is aware of the card insertion, it turns on the FET switch to apply power to card's VDD pin.

Once the card is inserted and all card pins are making contact, there should be a delay before the FET switch is turned on.

Note: Because there are clamping diodes on the CMD, CLK, and DAT0-3 pins, it is crucial to ensure that CLK, CMD, and DAT0-3 are at zero (0) volts during the delay and before the FET switch is turned on. If any I/O pin, (CMD, CLK, or DAT0-3) goes above zero volts during the delay and before power reaches the card VDD pin, it will forward bias the clamping diodes and can cause the card to go into an unknown state. It is the host's responsibility to make sure power gets to VDD before CMD, CLK, or DAT0-3 go above zero volts.

### 3.4.2 Bus Operating Conditions

SPI Mode bus operating conditions are identical to SD Card Bus Mode operating conditions. For details, see Section 6.6 of the SDA Physical Layer Specification, Version 3.01.

### 3.4.3 Bus Timing

See SDA Physical Layer Specification, Version 3.01.

## 3.5 microSD Card Product Family Registers

There is a set of eight registers within the card interface. However, the DSR Register is optional and is not used in the SanDisk microSD Card Product Family. For specific information about all registers, refer to Section 5 of the SDA Physical Layer Specification, Version 3.01.

### 3.5.1 Operation Conditions Register

The Operation Conditions Register (OCR) stores a card's VDD voltage profile. Refer to Section 5.1 of the SDA Physical Layer Specification, Version 3.01 for more information.

### 3.5.2 Card Identification Register

The Card Identification (CID) Register is 16 bytes long and contains the unique card identification number. It is programmed during card manufacturing and cannot be changed by card hosts. See Table 8.

**Table 6: CID Register Definitions**

Name	Type	Width	CID Value	Comments												
Manufacturer ID (MID)	Binary	8	0x03	Manufacturer IDs are controlled and assigned by the SD-3C, LLC												
OEM/Application ID (OID)	ASCII	16	SD ASCII Code 0x53, 0x44	Identifies the card OEM and/or the card contents. The OID is controlled and assigned by the SD-3C, LLC												
Product Name (PNM)	ASCII	40	<table border="1"> <thead> <tr> <th>SKU prefix</th> <th>Value1</th> <th>Value2</th> </tr> </thead> <tbody> <tr> <td>S D S D Q A B</td> <td>S U X X G</td> <td>S S X X G</td> </tr> <tr> <td>S D S D Q A D</td> <td>S U X X G</td> <td>S L X X G</td> </tr> <tr> <td>S D S D Q A E</td> <td>S U X X G</td> <td>S E X X G</td> </tr> </tbody> </table>	SKU prefix	Value1	Value2	S D S D Q A B	S U X X G	S S X X G	S D S D Q A D	S U X X G	S L X X G	S D S D Q A E	S U X X G	S E X X G	Five-character ASCII string. Product Name could be either Value1 or Value2. XXG = 04G,08G,16G,32G,64G, or 128, 200 referring to capacity (note: 128 and 200 are 128GB and 200GB card, respectively)
			SKU prefix	Value1	Value2											
			S D S D Q A B	S U X X G	S S X X G											
			S D S D Q A D	S U X X G	S L X X G											
S D S D Q A E	S U X X G	S E X X G														
Product Revision (PRV)	BCD	8	Product Revision xx	See Section 5.2 in the SDA Physical Layer Specification, Version 3.01.												
Serial Number (PSN)	Binary	32	Product serial number	32-bit unsigned integer												
Reserved	-	4	-	-												
Manufacturer Date Code (MDT)	BCD	12	Manufacture date (for example, April 2001=0x014)	Manufacturing date–ymm (offset from 2000)												
CRC7 Checksum (CRC)	Binary	7	CRC7	Calculated												
Not used, always 1	-	1	-	-												

### 3.5.3 Card Specific Data Register

The Card Specific Data (CSD) Register configuration information is required to access card data. The CSD defines the data format, error correction type, maximum data access time, etc. The field structures of the CSD Register vary depending on the physical specifications and card capacity. The CSD\_STRUCTURE field in the CSD Register indicates which structure version is used. Table 9 shows the version number as it relates to the CSD structure. Refer to Section 5.3.1 of the SDA Physical Layer Specification, Version 3.01 for more information.

**Table 7: CSD Register Structure**

CSD_Structure	CSD Structure Version	Valid for SD Card Physical Specification / Card Capacity
0	CSD Version 1.0	Version 1.01 to 1.10 Version 2.00/Standard Capacity
1	CSD Version 2.0	Version 2.00/High Capacity and

		Extended Capacity
2-3	Reserved	-

Table 8 provides an overview of the CSD Register. More field-specific information can be found in Section 5.3.2 of the SDA Physical Layer Specification, Version 3.01.

**Table 8: CSD Register (CSD Version 1.0)**

Field	Typical CSD Value	Description
CSD_STRUCTURE	1.0	CSD Structure
-	-	Reserved
TAAC	1.5 msec	Data read access-time-1
NSAC	0	Data read access-time-2 in CLK cycles (NSAC*100)
TRANS_SPEED	Standard Mode 25 MHz High Performance Mode 50MHz Ultra High Speed Mode-I 104MHz	Maximum data transfer rate
CCC	All (inc. WP, lock/unlock)	Card command classes
READ_BLK_LEN	2G = 0xA Up to 1G – 0x9	Maximum read data block length
READ_BLK_PARTIAL	Yes	Partial blocks for read allowed
WRITE_BLK_MISALIGN	No	Write block misalignment
READ_BLK_MISALIGN	No	Read block misalignment
DSR_IMP	No	DSR implemented
-	-	Reserved
C_SIZE 1 GB 2 GB	Secured 0xF22 0xF24	Device size
VDD_R_CURR_MIN	100 mA	Maximum read current @V <sub>DD</sub> min
VDD_R_CURR_MAX	80 mA	Maximum read current @V <sub>DD</sub> max
VDD_W_CURR_MIN	100 mA	Maximum write current @V <sub>DD</sub> min
VDD_W_CURR_MAX	80 mA	Maximum write current @V <sub>DD</sub> max
C_SIZE_MULT	2G=2048 1G-1024	Device size multiplier
ERASE_BLK_EN	Yes	Erase single block enable
SECTOR_SIZE	31 blocks	Erase sector size
WP_GRP_SIZE	127 sectors	Write protect group size
WP_GRP_ENABLE	Yes	Write protect group enable
Reserved	-	Reserved for MMC compatibility
R2W_FACTOR	X16	Write speed factor
WRITE_BLK_LEN	0x9	Maximum write data block length
WRITE_BLK_PARTIAL	No	Partial blocks for write allowed
-	-	Reserved
FILE_FORMAT_GRP	0	File format group
COPY	Has been copied	Copy flag (OTP)
PERM_WRITE_PROTECT	Not protected	Permanent write protection
TMP_WRITE_PROTECT	Not protected	Temporary write protection

Field	Typical CSD Value	Description
FILE_FORMAT	HD w/partition	File format
Reserved	-	Reserved
CRC	CRC7	CRC
-	-	Not used, always "1"

Refer to Section 5.3.3, Table 5-16 of the SDA Physical Layer Specification, Version 3.01 for more detailed information.

**Table 9: CSD Register (CSD Version 2.0)**

Field	Typical CSD Value	Description
CSD_STRUCTURE	2.0	CSD Structure
-	-	Reserved
TAAC	1.5 msec	Data read access-time
NSAC	0	Data read access-time-2 in CLK cycles (NSAC*100)
TRANS_SPEED	Standard Mode 25 MHz High Performance Mode 50MHz Ultra High Speed Mode 104MHz	Maximum data transfer rate
CCC	All (inc. WP, lock/unlock)	Card command classes
READ_BLK_LEN	9	Maximum read data block length
READ_BLK_PARTIAL	Yes	Partial blocks for read allowed
WRITE_BLK_MISALIGN	No	Write block misalignment
READ_BLK_MISALIGN	No	Read block misalignment
DSR_IMP	No	DSR implemented
-	0	Reserved
C_SIZE	See SDA Physical Layer Specification	Device size
-	0	Reserved
ERASE_BLK_EN	1	Erase single block enable
SECTOR_SIZE	64 blocks	Erase sector size
WP_GRP_SIZE	000000b	Write protect group size
WP_GRP_ENABLE	No	Write protect group enable
Reserved	-	Reserved for MMC compatibility
R2W_FACTOR	X4	Write speed factor
WRITE_BLK_LEN		Maximum write data block length
WRITE_BLK_PARTIAL	No	Partial blocks for write allowed
-	-	Reserved
FILE_FORMAT_GRP	0	File format group
COPY	Has been copied	Copy flag (OTP)
PERM_WRITE_PROTECT	Not protected	Permanent write protection
TMP_WRITE_PROTECT	Not protected	Temporary write protection
FILE_FORMAT	HD w/partition	File format
Reserved	-	Reserved
CRC	CRC7	CRC

Field	Typical CSD Value	Description
-	-	Not used, always "1"

### 3.5.4 Card Status Register

The Card Status Register (CSR) transmits the card's status information (which may be stored in a local status register) to the host. The CSR is defined in Section 4.10.1 in the SDA Physical Layer Specification, Version 3.01.

### 3.5.5 SD Status Register

The SD Status Register (SSR) contains status bits that are related to the microSD Card proprietary features and may be used for future applications. The SD Status structure is described in Section 4.10.2 in the SDA Physical Layer Specification, Version 3.01.

### 3.5.6 Relative Card Address Register

The 16-bit Relative Card Address (RCA) Register carries the card address published by the card during the card identification. Refer to Section 5.4 in the SDA Physical Layer Specification, Version 3.01 for more information.

### 3.5.7 SD Card Configuration Register

The SD Card Configuration Register (SCR) is in addition to the CSD Register. The SCR provides information about special features in the SanDisk SD Card products. For more information, refer to Section 5.6 in the SDA Physical Layer Specification, Version 3.01.

### 3.5.8 microSD Card Product Family Registers in SPI Mode

All card registers are accessible in SPI Mode. Their format is identical to the format in the SD Bus Mode; however a few fields are irrelevant in SPI Mode. In SPI Mode, the Card Status Register also has a different, shorter format. Refer to Section 7.4 in the SDA Physical Layer Specification, Version 3.01 for more details.

### 3.5.9 Data Interchange Format and Card Sizes

In general, a file system provides structure for data in SanDisk microSD Card products. The SD Card File System Specification, published by the SDA, describes the file format system that is implemented in the microSD Card products. In general, each card is divided into two separate DOS-formatted partitions as follows:

- User Area—used for secured and non-secured data storage and can be accessed by the user with regular read/write commands.
- Security Protected Area—used by content protection applications to save security related data and can be accessed by the host using the secured read/write command after doing authentication as defined in the SD Security Specification. The security protected area size is defined by SanDisk as approximately one percent of the total size of the card.

**Table 10: Minimum User Area DOS Image Parameters**

Capacity <sup>1</sup>	Total LBAs <sup>2</sup>	No. of Partition System Area Sectors <sup>2</sup>	Total Partition Sectors <sup>2</sup>	User Data Sectors <sup>2</sup>	User Data Bytes <sup>2</sup>
200GB	384503808	32768	384471040	384438272	196832395264
128GB	249736192	32768	249703424	249670656	127831375872
64GB	124735488	32768	124702720	124669952	63831015424
32GB	62333952	8192	62325760	62309376	31902400512
16GB	31116288	8192	31108096	31099904	15923150848
8GB	15523840	8192	15515648	15507456	7939817472
4GB	7744512	8192	7736320	7728128	3956801536

<sup>1</sup> 1 (GB) = 1 billion bytes. Some capacity not available for data storage.

<sup>2</sup> Total LBAs, Number of Partition System Area Sectors, Total Partition Sectors, User Data Sectors and User Data Bytes are minimum values. Actual values may vary depending on flash technology used.

## 4 MICROSD CARD PROTOCOL DESCRIPTION

### 4.1 General Description

SD Protocol information for cards in the SanDisk microSD Card Product Family is contained in this chapter; information includes SD bus protocol, card identification, and a functional description.

### 4.2 SD Bus Protocol

Communication over the SD bus is based on command and data-bit streams initiated by a start bit and terminated by a stop bit. See Section 3.6.1 of the SDA Physical Layer Specification, Version 3.01 for details.

### 4.3 Functional Description

In the SanDisk microSD Card Product Family, the host controls all communication between itself and the cards. This section provides a general overview of the card identification and data transfer modes; commands; card dependencies; various card operation modes and restrictions for controlling the clock signal. For SD Card commands, together with corresponding responses, state transitions, error conditions, and timings refer to Section 4 of the SDA Physical Layer Specification, Version 3.01.

#### 4.3.1 Card Identification Mode

In Card Identification Mode, the host resets all cards, validates operation voltage range, identifies and requests cards to publish a relative card address. For more information see Section 4.2 in the SDA Physical Layer Specification, Version 3.01.

#### 4.3.2 Data Transfer Mode

Functionality of the Data Transfer Mode can be found in Section 4.3 of the SDA Physical Layer Specification, Version 3.01. This section includes information about data read and write, erase, write-protect management, card lock/unlock operations,

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application-specific commands, switch function command, high-speed mode, command system, and the Send Interface Condition command (CMD8). CMD8 is part of identification mode and command functional differences in microSD cards.

### **4.3.3 Clock Control**

The host can use the bus clock signal in SanDisk microSD cards to switch them to energy saving mode or to control data flow on the bus. See Section 4.4 of the SDA Physical Layer Specification, Version 3.01.

### **Cyclic Redundancy Codes**

The Cyclic Redundancy Check (CRC) protects against transmission errors that may occur on the bus in SanDisk microSD Card Product Family cards. Detailed information and examples for CRC7 and CRC16 are provided in Section 4.5 of the SDA Physical Layer Specification, Version 3.01.

### **4.3.4 Error Conditions**

See Section 4.6 of the SDA Physical Layer Specification, Version 3.01.

### **4.3.5 Commands**

See Section 4.7 of the SDA Physical Layer Specification, Version 3.01 for detailed information about card commands in the SanDisk microSD Card Product Family.

### **4.3.6 Card State Transition**

In microSD cards, the state transition is dependent on the received command. The transition is defined in Section 4.8 of the SDA Physical Layer Specification, Version 3.01 along with responses sent on the command line.

### **4.3.7 Timing Diagrams and Values**

See Section 4.12 of the SDA Physical Layer Specification, Version 3.01.

### **4.3.8 Speed Class Specification**

SDA speed class specification classifies card minimum write performance by speed class number and offers the method to test performance. For more information, refer to Section 4.13 of the SDA Physical Layer Specification, Version 3.01.

### **4.3.9 Erase Timeout Calculation**

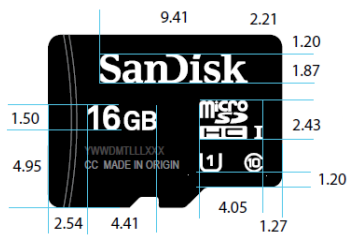
See Section 4.14 of the SDA Physical Layer Specification, Version 3.01.



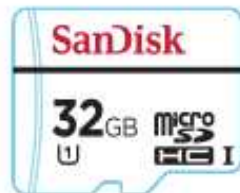
## 5 MARKING



Performance microSD Cards



Premier microSD Cards



Superior microSD Cards

**Figure 5: Marking Specs for  
microSD, microSDHC, microSDXC Cards**

## 6 ORDERING INFORMATION

To order SanDisk products directly from SanDisk, please contact your local sales office.

Part Number	Capacity <sup>2</sup>	Interface	Speed Class <sup>1</sup>
SDSDQAB-004G	4 GB	UHS-I 50	Sequential Write: 5 MB/s Sequential Read: 20 MB/s SC4
SDSDQAB-008G	8 GB		
SDSDQAB-016G	16 GB		
SDSDQAB-032G	32 GB		
SDSDQAB-064G	64 GB		
SDSDQAD-008G	8 GB	UHS-I 50	Sequential Write: 10 MB/s Sequential Read: 40 MB/s U1/SC10
SDSDQAD-016G	16 GB		
SDSDQAD-032G	32 GB		
SDSDQAD-064G	64 GB		
SDSDQAD-128G	128 GB		
SDSDQAD-200G	200GB	UHS-I 104	Sequential Write: 10 MB/s Sequential Read: 80 MB/s U1/SC10
SDSDQAE-032G	32 GB	UHS-I 104	Sequential Write: 50 MB/s Sequential Read: 80 MB/s U3/SC10
SDSDQAE-064G	64 GB		

1. Based on SanDisk internal testing; performance may be lower depending upon host device. 1 megabyte (MB) = 1 million bytes.

2. 1 gigabyte (GB) = 1 billion bytes. Some capacity not available for data storage.